



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 10/791,191

Filed: March 2, 2004

For: METHODS OF IMPROVING
COPPER INTERCONNECTS OF
SEMICONDUCTOR DEVICES FOR
BONDING

Confirmation No.: Unknown

Examiner: Unknown

Group Art Unit: Unknown

Attorney Docket No.: 2269-3854.3US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

May 3, 2004
Date

Signature

Deidra J. Pfeil
Name (Type/Print)

PRELIMINARY AMENDMENT

Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Claims are reflected in the listing which begins on page 5 of this paper.

Amendments to the Drawings appear on page 7 of this paper and include both an attached replacement sheet and an annotated sheet showing changes.

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Remarks begin on page 8 of this paper.

An **Appendix** including amended drawing figures is attached following page 8. of this paper.